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Details	
Product Status	Obsolete
Number of LABs/CLBs	7612
Number of Logic Elements/Cells	181165
Total RAM Bits	10177536
Number of I/O	372
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	780-BBGA, FCBGA
Supplier Device Package	780-FBGA (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2agx190ef29i5n

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Table 1–11. OCT With and Without Calibration Specification for Arria II GX Device I/Os (Note 1) (Part 2 of 2)

Combal	Description	Conditions (II)	Calibration	II.m.i.k	
Symbol	Description	Conditions (V)	Commercial	Industrial	Unit
50-Ω R _S 3.0, 2.5, 1.8, 1.5, 1.2	50-Ω series OCT with calibration	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	± 10	± 10	%
100-Ω R _D 2.5	100-Ω differential OCT without calibration	V _{CCIO} = 2.5	± 30	± 30	%

Note to Table 1-11:

(1) OCT with calibration accuracy is valid at the time of calibration only.

Table 1–12 lists the OCT termination calibration accuracy specifications for Arria II GZ devices.

Table 1–12. OCT with Calibration Accuracy Specifications for Arria II GZ Devices (Note 1)

		6 1111 (115	Ca	libration Accura	cy	
Symbol	Description	Conditions (V)	C2	C3,I3	C4,I4	Unit
25-Ω R _S 3.0, 2.5, 1.8, 1.5, 1.2 <i>(2)</i>	25-Ω series OCT with calibration	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	± 8	± 8	± 8	%
50-Ω R _S 3.0, 2.5, 1.8, 1.5, 1.2	50- Ω internal series OCT with calibration	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	± 8	± 8	± 8	%
50-Ω R _T 2.5, 1.8, 1.5, 1.2	$50-\Omega$ internal parallel OCT with calibration	$V_{CCIO} = 2.5, 1.8,$ 1.5, 1.2	± 10	± 10	± 10	%
20- Ω , 40- Ω , and 60- Ω R _S 3.0, 2.5, 1.8, 1.5, 1.2 (3)	$20-\Omega$, $40-\Omega$ and $60-\Omega$ R _S expanded range for internal series OCT with calibration	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	± 10	± 10	± 10	%
25-Ω R _{S_left_shift} 3.0, 2.5, 1.8, 1.5, 1.2	25-Ω R _{S_left_shift} internal left shift series OCT with calibration	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	± 10	± 10	± 10	%

Notes to Table 1-12:

- (1) OCT calibration accuracy is valid at the time of calibration only.
- (2) 25- Ω R_S is not supported for 1.5 V and 1.2 V in Row I/O.
- (3) $20-\Omega$ R_S is not supported for 1.5 V and 1.2 V in Row I/O.

Use the following with Equation 1–1:

- \blacksquare R_{SCAL} is the OCT resistance value at power up.
- lacktriangle ΔT is the variation of temperature with respect to the temperature at power up.
- lacksquare ΔV is the variation of voltage with respect to the V_{CCIO} at power up.
- \blacksquare dR/dT is the percentage change of R_{SCAL} with temperature.
- $\,\blacksquare\,\, dR/dV$ is the percentage change of R_{SCAL} with voltage.

Table 1–14 lists the OCT variation with temperature and voltage after power-up calibration for Arria II GX devices.

Table 1–14. OCT Variation after Power-up Calibration for Arria II GX Devices

Nominal Voltage V _{CC10} (V)	dR/dT (%/°C)	dR/dV (%/mV)
3.0	0.262	0.035
2.5	0.234	0.039
1.8	0.219	0.086
1.5	0.199	0.136
1.2	0.161	0.288

Table 1–15 lists the OCT variation with temperature and voltage after power-up calibration for Arria II GZ devices.

Table 1–15. OCT Variation after Power-Up Calibration for Arria II GZ Devices (Note 1)

Nominal Voltage, V _{ccio} (V)	dR/dT (%/°C)	dR/dV (%/mV)
3.0	0.189	0.0297
2.5	0.208	0.0344
1.8	0.266	0.0499
1.5	0.273	0.0744
1.2	0.317	0.1241

Note to Table 1-15:

Pin Capacitance

Table 1–16 lists the pin capacitance for Arria II GX devices.

Table 1–16. Pin Capacitance for Arria II GX Devices

Symbol	Description	Typical	Unit
C ₁₀	Input capacitance on I/O pins, dual-purpose pins (differential I/O, clock, $R_{up},R_{dn}),$ and dedicated clock input pins	7	pF

⁽¹⁾ Valid for V_{CCIO} range of ±5% and temperature range of 0° to 85°C.

Table 1–19 lists the weak pull-up resistor values for Arria II GZ devices.

Table 1–19. Internal Weak Pull-Up Resistor for Arria II GZ Devices (Note 1), (2)

Symbol	Description	Conditions	Min	Тур	Max	Unit
	Value of the I/O pin pull-up resistor before and during	$V_{CCIO} = 3.0 \text{ V } \pm 5\%$ (3)		25	_	kΩ
		$V_{CCIO} = 2.5 \text{ V } \pm 5\%$ (3)	_	25	_	kΩ
R _{PU}	configuration, as well as user	$V_{CCIO} = 1.8 \text{ V } \pm 5\%$ (3)	_	25	_	kΩ
	mode if the programmable pull-up resistor option is enabled.	$V_{CCIO} = 1.5 \text{ V } \pm 5\%$ (3)	_	25	_	kΩ
	pull-up resistor option is enabled.	$V_{CCIO} = 1.2 \text{ V } \pm 5\%$ (3)	_	25	_	kΩ

Notes to Table 1-19:

- (1) All I/O pins have an option to enable weak pull-up except configuration, test, and JTAG pins.
- (2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 k Ω .
- (3) Pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO} .

Hot Socketing

Table 1–20 lists the hot-socketing specification for Arria II GX and GZ devices.

Table 1–20. Hot Socketing Specifications for Arria II Devices

Symbol	Description	Maximum
I _{IIOPIN(DC)}	DC current per I/O pin	300 μΑ
I _{IOPIN(AC)}	AC current per I/O pin	8 mA (1)
I _{XCVRTX(DC)}	DC current per transceiver TX pin	100 mA
I _{XCVRRX(DC)}	DC current per transceiver RX pin	50 mA

Note to Table 1-20:

Schmitt Trigger Input

The Arria II GX device supports Schmitt trigger input on the TDI, TMS, TCK, nSTATUS, nCONFIG, nCE, CONF_DONE, and DCLK pins. A Schmitt trigger feature introduces hysteresis to the input signal for improved noise immunity, especially for signals with slow edge rates.

Table 1–21 lists the hysteresis specifications across the supported V_{CCIO} range for Schmitt trigger inputs in Arria II GX devices.

Table 1–21. Schmitt Trigger Input Hysteresis Specifications for Arria II GX Devices

Symbol	Description	Condition (V)	Minimum	Unit
		V _{CCIO} = 3.3	220	mV
V	Hysteresis for Schmitt trigger input	V _{CCIO} = 2.5	180	mV
V _{Schmitt}	hysteresis for Schillitt trigger input	V _{CCIO} = 1.8	110	mV
		V _{CCIO} = 1.5	70	mV

⁽¹⁾ The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{10PIN}| = C dv/dt$, in which "C" is I/O pin capacitance and "dv/dt" is slew rate.

I/O Standard Specifications

Table 1–22 through Table 1–35 list input voltage (V_{IH} and V_{IL}), output voltage (V_{OH} and V_{OL}), and current drive characteristics (I_{OH} and I_{OL}) for various I/O standards supported by the Arria II device family. They also show the Arria II device family I/O standard specifications. V_{OL} and V_{OH} values are valid at the corresponding I_{OH} and I_{OL} , respectively.



For an explanation of terms used in Table 1–22 through Table 1–35, refer to "Glossary" on page 1–74.

Table 1–22 lists the single-ended I/O standards for Arria II GX devices.

Table 1-22. Single-Ended I/O Standards for Arria II GX Devices

I/O Standard		V _{CCIO} (V)		VII	_ (V)	V _{IH}	_I (V)	V _{OL} (V)	V _{OH} (V)	I _{OL}	I _{OH}
I/O Standard	Min	Тур	Max	Min	Max	Min	Max	Max	Min	(mÅ)	(mA)
3.3 V LVTTL	3.135	3.3	3.465	-0.3	0.8	1.7	3.6	0.45	2.4	4	-4
3.3 V LVCMOS	3.135	3.3	3.465	-0.3	0.8	1.7	3.6	0.2	V _{CCIO} -0.2	2	-2
3.0 V LVTTL	2.85	3	3.15	-0.3	0.8	1.7	V _{CCIO} + 0.3	0.45	2.4	4	-4
3.0 V LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	V _{CCIO} + 0.3	0.2	V _{CCIO} - 0.2	0.1	-0.1
2.5 V LVCMOS	2.375	2.5	2.625	-0.3	0.7	1.7	V _{CCIO} + 0.3	0.4	2	1	-1
1.8 V LVCMOS	1.71	1.8	1.89	-0.3	0.35 × V _{CCIO}	0.65 × V _{CCIO}	V _{CCIO} + 0.3	0.45	V _{CCIO} - 0.45	2	-2
1.5 V LVCMOS	1.425	1.5	1.575	-0.3	0.35 × V _{CCIO}	0.65 × V _{CCIO}	V _{CCIO} + 0.3	0.25 × V _{CCIO}	0.75 × V _{CCIO}	2	-2
1.2 V LVCMOS	1.14	1.2	1.26	-0.3	0.35 × V _{CCIO}	0.65 × V _{CCIO}	V _{CCIO} + 0.3	0.25 × V _{CCIO}	0.75 × V _{CCIO}	2	-2
3.0-V PCI	2.85	3	3.15	_	0.3 × V _{CCIO}	0.5 × V _{CCIO}	V _{CCIO} + 0.3	0.1 × V _{CCIO}	0.9 × V _{CCIO}	1.5	-0.5
3.0-V PCI-X	2.85	3	3.15	_	0.35 × V _{CCIO}	0.5 × V _{CCIO}	V _{CCIO} + 0.3	0.1 × V _{CCIO}	0.9 × V _{CCIO}	1.5	-0.5

Table 1–23 lists the single-ended I/O standards for Arria II GZ devices.

Table 1–23. Single-Ended I/O Standards for Arria II GZ Devices (Part 1 of 2)

I/O Otomdond		V _{CCIO} (V)		V _{IL} (V)		V _{IH} (V)		V _{OL} (V)	V _{OH} (V)	I _{OL}	I _{OH}
I/O Standard	Min	Тур	Max	Min	Max	Min	Max	Max	Min	(mĀ)	(mÄ)
LVTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	V _{CCIO} - 0.2	0.1	-0.1
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	0.35 × V _{CCIO}	0.65 × V _{CCIO}	V _{CCIO} + 0.3	0.45	V _{CCIO} - 0.45	2	-2
1.5 V	1.425	1.5	1.575	-0.3	0.35 × V _{CCIO}	0.65 × V _{CCIO}	V _{CCIO} + 0.3	0.25 × V _{CCIO}	0.75 × V _{CCIO}	2	-2

Table 1–26 lists the single-ended SSTL and HSTL I/O standard signal specifications for Arria II GX devices.

Table 1–26. Single-Ended SSTL and HSTL I/O Standard Signal Specifications for Arria II GX Devices

I/O Ctondord	V _{IL(D(}	;) (V)	V _{IH(D}	_{C)} (V)	V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{OL} (V)	V _{OH} (V)	I _{OL}	I _{OH}
I/O Standard	Min	Max	Min	Max	Max	Min	Max	Min	(mA)	(mA)
SSTL-2 Class I	-0.3	V _{REF} - 0.18	V _{REF} + 0.18	V _{CCIO} + 0.3	V _{REF} - 0.35	V _{REF} + 0.35	V _{TT} - 0.57	V _{TT} + 0.57	8.1	-8.1
SSTL-2 Class II	-0.3	V _{REF} - 0.18	V _{REF} + 0.18	V _{CCIO} + 0.3	V _{REF} - 0.35	V _{REF} + 0.35	V _{TT} - 0.76	V _{TT} + 0.76	16.4	-16.4
SSTL-18 Class I	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} - 0.25	V _{REF} + 0.25	V _{TT} - 0.475	V _{TT} + 0.475	6.7	-6.7
SSTL-18 Class II	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} - 0.25	V _{REF} + 0.25	0.28	V _{CCIO} - 0.28	13.4	-13.4
SSTL-15 Class I	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	V _{CCIO} + 0.3	V _{REF} - 0.175	V _{REF} + 0.175	0.2 × V _{CCIO}	0.8 × V _{CCIO}	8	-8
SSTL-15 Class II	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	V _{CCIO} + 0.3	V _{REF} - 0.175	V _{REF} + 0.175	0.2 × V _{CCIO}	0.8 × V _{CCIO}	16	-16
HSTL-18 Class I	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	V _{CCIO} + 0.3	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} - 0.4	8	-8
HSTL-18 Class II	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	V _{CCIO} + 0.3	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} - 0.4	16	-16
HSTL-15 Class I	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	V _{CCIO} + 0.3	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} - 0.4	8	-8
HSTL-15 Class II	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	V _{CCIO} + 0.3	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} - 0.4	16	-16
HSTL-12 Class I	-0.15	V _{REF} - 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} - 0.15	V _{REF} + 0.15	0.25 × V _{CCIO}	0.75 × V _{CCIO}	8	-8
HSTL-12 Class II	-0.15	V _{REF} - 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} - 0.15	V _{REF} + 0.15	0.25 × V _{CCIO}	0.75 × V _{CCIO}	14	-14

Table 1–27 lists the single-ended SSTL and HSTL I/O standard signal specifications for Arria II GZ devices.

Table 1–27. Single-Ended SSTL and HSTL I/O Standards Signal Specifications for Arria II GZ Devices (Part 1 of 2)

				_	_			-	_	
I/O Standard	V _{IL(D}	_{C)} (V)	V _{IH(D}	_{C)} (V)	V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{OL} (V)	V _{OH} (V)	I _{OL}	I _{OH}
i/O Stanuaru	Min	Max	Min	Max	Max	Min	Max	Min	(mA)	(mA)
SSTL-2 Class I	-0.3	V _{REF} - 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} - 0.31	V _{REF} + 0.31	V _{TT} - 0.57	V _{TT} + 0.57	8.1	-8.1
SSTL-2 Class II	-0.3	V _{REF} - 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} - 0.31	V _{REF} + 0.31	V _{TT} - 0.76	V _{TT} + 0.76	16.2	-16.2
SSTL-18 Class I	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} - 0.25	V _{REF} + 0.25	V _{TT} - 0.475	V _{TT} + 0.475	6.7	-6.7
SSTL-18 Class II	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} - 0.25	V _{REF} + 0.25	0.28	V _{CCIO} - 0.28	13.4	-13.4
SSTL-15 Class I	_	V _{REF} - 0.1	V _{REF} + 0.1	_	V _{REF} - 0.175	V _{REF} + 0.175	0.2 × V _{CCIO}	0.8 × V _{CCIO}	8	-8

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Switching Characteristics

This section provides performance characteristics of the Arria II GX and GZ core and periphery blocks for commercial grade devices. The following tables are considered final and are based on actual silicon characterization and testing. These numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions.

Transceiver Performance Specifications

Table 1–34 lists the Arria II GX transceiver specifications.

Table 1-34. Transceiver Specifications for Arria II GX Devices (Note 1) (Part 1 of 7)

Symbol/	0		13			C4			C5 and I	5		C6		11
Description	Condition	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Reference Clock	•		•	•										
Supported I/O Standards			1	.2-V PCML,	1.5-V P(CML, 2.5-\	/ PCML, Diff	erential LV	PECL, LVD	S, and HCS	L			
Input frequency from REFCLK input pins	_	50	_	622.08	50	_	622.08	50	_	622.08	50	_	622.08	MHz
Input frequency from PLD input	_	50	_	200	50	_	200	50	_	200	50	_	200	MHz
Absolute V_{MAX} for a REFCLK pin	_	_	_	2.2	_	_	2.2	_	_	2.2	_	_	2.2	V
Absolute V_{MIN} for a REFCLK pin	_	-0.3	_	_	-0.3	_	_	-0.3	_	_	-0.3	_	_	V
Rise/fall time (2)	_	_	_	0.2	_	_	0.2	_	_	0.2	_	_	0.2	UI
Duty cycle	_	45	_	55	45		55	45	_	55	45	_	55	%
Peak-to-peak differential input voltage	_	200	_	2000	200	_	2000	200	_	2000	200	_	2000	mV
Spread-spectrum modulating clock frequency	PCIe	30	_	33	30	_	33	30	_	33	30	_	33	kHz

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Table 1-34. Transceiver Specifications for Arria II GX Devices (Note 1) (Part 3 of 7)

Symbol/	0		13			C4			C5 and IS	5		C6		1111
Description	Condition	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
fixedclk clock frequency	PCIe Receiver Detect	_	125	_	_	125	_	_	125	_	_	125	_	MHz
reconfig_ clk clock frequency	Dynamic reconfig. clock frequency	2.5/ 37.5 <i>(4)</i>	_	50	2.5/ 37.5 (4)	_	50	2.5/ 37.5 (4)	_	50	2.5/ 37.5 (4)	_	50	MHz
Delta time between reconfig_ clks (5)	_	_	_	2	_	_	2	_	_	2	_	_	2	ms
Transceiver block minimum power-down pulse width	_	_	1	_	_	1	_	_	1	_	_	1	_	μѕ
Receiver														
Supported I/O Standards				1.4-V PCN	1L, 1.5-V	PCML, 2.	5-V PCML, 2	2.5-V PCM	L, LVPECL,	and LVDS				
Data rate (13)	_	600	_	6375	600	_	3750	600		3750	600	_	3125	Mbps
Absolute V _{MAX} for a receiver pin (6)	_		_	1.5	_	_	1.5		_	1.5	_		1.5	V
Absolute V _{MIN} for a receiver pin	_	-0.4	_	_	-0.4	_	_	-0.4	_	_	-0.4	_	_	V
Maximum peak-to-peak	V _{ICM} = 0.82 V setting	_	_	2.7	_	_	2.7	_	_	2.7	_	_	2.7	V
differential input voltage V _{ID} (diff p-p)	V _{ICM} =1.1 V setting (7)	_	_	1.6	_		1.6	_	_	1.6	_	_	1.6	V

Table 1-34. Transceiver Specifications for Arria II GX Devices (Note 1) (Part 7 of 7)

Symbol/ Condition			13			C4			C5 and I5	j		C6		Unit
Description	cription Condition	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Ullit
Digital reset pulse width	_					М	inimum is 2	parallel clo	ock cycles					

Notes to Table 1-34:

- (1) For AC-coupled links, the on-chip biasing circuit is switched off before and during configuration. Ensure that input specifications are not violated during this period.
- (2) The rise/fall time is specified from 20% to 80%.
- (3) To calculate the REFCLK rms phase jitter requirement at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f (MHz) = REFCLK rms phase jitter at 100 MHz * 100/f.
- (4) The minimum reconfig_clk frequency is 2.5 MHz if the transceiver channel is configured in **Transmitter only** mode. The minimum reconfig_clk frequency is 37.5 MHz if the transceiver channel is configured in **Receiver only** or **Receiver and Transmitter** mode. For more information, refer to AN 558: Implementing Dynamic Reconfiguration in Arria II Devices.
- (5) If your design uses more than one dynamic reconfiguration controller instances (altgx_reconfig) to control the transceiver channels (altgx) physically located on the same side of the device, and if you use different reconfig_clk sources for these altgx_reconfig instances, the delta time between any two of these reconfig_clk sources becoming stable must not exceed the maximum specification listed.
- (6) The device cannot tolerate prolonged operation at this absolute maximum.
- (7) You must use the 1.1-V RX V_{ICM} setting if the input serial data standard is LVDS and the link is DC-coupled.
- (8) The rate matcher supports only up to ± 300 parts per million (ppm).
- (9) Time taken to rx pll locked goes high from rx analogreset de-assertion. Refer to Figure 1-1.
- (10) The time in which the CDR must be kept in lock-to-reference mode after rx pll locked goes high and before rx locktodata is asserted in manual mode. Refer to Figure 1-1.
- (11) The time taken to recover valid data after the rx locktodata signal is asserted in manual mode. Refer to Figure 1–1.
- (12) The time taken to recover valid data after the rx freqlocked signal goes high in automatic mode. Refer to Figure 1-2.
- (13) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.

Chapter 1: Device Datasheet for Arria II Devices Switching Characteristics

Table 1–35. Transceiver Specifications for Arria II GZ Devices (Part 5 of 5)

Symbol/	Conditions	-(C3 and –I3	(1)		-C4 and -	I 4	Ilmit
Description	Conditions	Min	Тур	Max	Min	Тур	Max	Unit
	PCIe Gen1			2.5 -	3.5			MHz
	PCIe Gen2			6 -	8			MHz
	(OIF) CEI PHY at 4.976 Gbps			7 -	11			MHz
-3 dB Bandwidth	(OIF) CEI PHY at 6.375 Gbps			5 -	10			MHz
	XAUI			2 -	4			MHz
	SRIO 1.25 Gbps			3 - 9	5.5			MHz
	SRIO 2.5 Gbps			3 - 9	5.5			MHz
	SRIO 3.125 Gbps			2 -	4			MHz
	GIGE			2.5 -	4.5			MHz
	SONET OC12			1.5 -	2.5			MHz
	SONET OC48			3.5	- 6			MHz
Transceiver-FPGA Fabric Int	erface							
Interface speed	_	25	_	325	25	_	250	MHz
Digital reset pulse width	_	Minimum is two parallel clock cycles						

Notes to Table 1-35:

- (1) The 3x speed grade is the fastest speed grade offered in the following Arria II GZ devices: EP2AGZ225, EP2AGZ300, and EP2AGZ350.
- (2) The rise and fall time transition is specified from 20% to 80%.
- (3) To calculate the REFCLK rms phase jitter requirement at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f (MHz) = REFCLK rms phase jitter at 100 MHz * 100/f.
- (4) The minimum reconfig_clk frequency is 2.5 MHz if the transceiver channel is configured in **Transmitter only** mode. The minimum reconfig_clk frequency is 37.5 MHz if the transceiver channel is configured in **Receiver only** or **Receiver and Transmitter** mode.
- (5) If your design uses more than one dynamic reconfiguration controller (altgx_reconfig) instances to control the transceiver (altgx) channels physically located on the same side of the device AND if you use different reconfig_clk sources for these altgx_reconfig instances, the delta time between any two of these reconfig_clk sources becoming stable must not exceed the maximum specification listed.
- (6) The device cannot tolerate prolonged operation at this absolute maximum.
- (7) You must use the 1.1-V RX V_{ICM} setting if the input serial data standard is LVDS.
- (8) The differential eye opening specification at the receiver input pins assumes that Receiver Equalization is disabled. If you enable Receiver Equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level. Use H-Spice simulation to derive the minimum eye opening requirement with Receiver Equalization enabled.
- (9) The rate matcher supports only up to \pm 300 ppm.
- (10) Time taken to rx_pll_locked goes high from rx_analogreset de-assertion. Refer to Figure 1-1 on page 1-33.
- (11) Time for which the CDR must be kept in lock-to-reference mode after rx_pll_locked goes high and before rx_locktodata is asserted in manual mode. Refer to Figure 1–1 on page 1–33.
- (12) Time taken to recover valid data after the rx locktodata signal is asserted in manual mode. Refer to Figure 1-1 on page 1-33.
- (13) Time taken to recover valid data after the rx freqlocked signal goes high in automatic mode. Refer to Figure 1-2 on page 1-33.
- (14) A GPLL may be required to meet the PMA-FPGA fabric interface timing above certain data rates. For more information, refer to the *Transceiver Clocking for Arria II Devices* chapter.
- (15) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (16) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.

Figure 1–1 shows the lock time parameters in manual mode.

LTD = lock-to-data. LTR = lock-to-reference.

Figure 1–1. Lock Time Parameters for Manual Mode

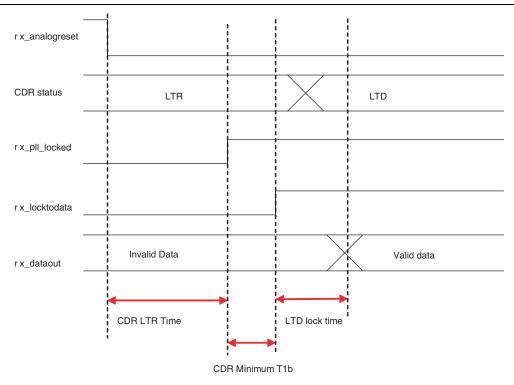


Figure 1–2 shows the lock time parameters in automatic mode.

Figure 1–2. Lock Time Parameters for Automatic Mode

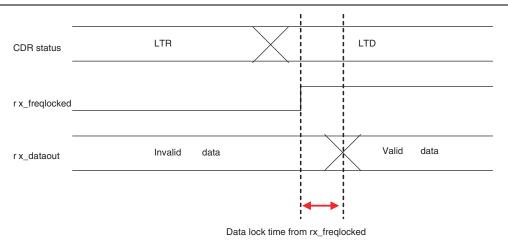


Table 1-40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 3 of 10)

Symbol/	0 1111		13			C4			C5, I	5		C6		
Description	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
PCIe Receiver Jitt	ter Tolerance <i>(4)</i>			•				•		•	•		•	•
Total jitter at 2.5 Gbps (Gen1)	Compliance pattern		> 0.6			> 0.6	;		> 0.6	6		> 0.6	6	UI
PCIe (Gen 1) Elect	rical Idle Detect Th	reshold	<i>(9)</i>											
VRX-IDLE- DETDIFF (p-p)	Compliance pattern	65	_	175	65	_	175	65	_	175	65	_	175	mV
Serial RapidIO® (S	RIO) Transmit Jitter	Genera	tion <i>(5)</i>								•	•		
Deterministic jitter (peak-to-peak)	Data Rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	_	_	0.17	_	_	0.17	_	_	0.17	_	_	0.17	UI
Total jitter (peak-to-peak)	Data Rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	_	_	0.35	_	_	0.35	_	_	0.35	_	_	0.35	UI
SRIO Receiver Jitt	ter Tolerance <i>(5)</i>				I				l					1
Deterministic jitter tolerance (peak-to-peak)	Data Rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT		> 0.37			> 0.3	7		> 0.3	7		> 0.3	7	UI
Combined deterministic and random jitter	Data Rate = 1.25, 2.5, 3.125 Gbps		> 0.55			> 0.5	5		> 0.5	5		> 0.5	5	UI
tolerance (peak-to-peak)	Pattern = CJPAT													
	Jitter frequency = 22.1 KHz Data rate = 1.25, 2.5, 3.125 Gbps		> 8.5			> 8.5	j		> 8.5	j		> 8.5	5	UI
	Pattern = CJPAT													
Sinusoidal jitter	Jitter frequency = 1.875 MHz													
tolerance (peak-to-peak)	Data rate = 1.25, 2.5, 3.125 Gbps		> 0.1			> 0.1			> 0.1			> 0.1		UI
(Fig. 1)	Pattern = CJPAT													
	Jitter frequency = 20 MHz													
	Data rate = 1.25, 2.5, 3.125 Gbps	> 0.1				> 0.1			> 0.1			> 0.1		UI
	Pattern = CJPAT													
GIGE Transmit Jitt	er Generation <i>(6)</i>	•						•						•
Deterministic jitter (peak-to-peak)	Pattern = CRPAT	_	_	0.14	_	_	0.14	_	_	0.14	_	_	0.14	UI

Table 1-40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 4 of 10)

Symbol/		I3				C4			C5, I	5		C6		
Description	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Total jitter	Pattern = CRPAT	_		0.27	_	_	0.279	_		0.279			0.279	UI
(peak-to-peak)	Tattom = OTITAL			9			0.270			0.270			0.270	0.
GIGE Receiver Jitt	er Tolerance <i>(6)</i>													1
Deterministic jitter tolerance (peak-to-peak)	Pattern = CJPAT		> 0.4			> 0.4	ļ		> 0.4	ļ		> 0.4		UI
Combined deterministic and random jitter tolerance (peak-to-peak)	Pattern = CJPAT		> 0.66			> 0.6	6		> 0.60	ô		> 0.60	ô	UI
HiGig Transmit Jit	ter Generation <i>(7)</i>													
Deterministic jitter	Data rate = 3.75 Gbps	_	_	0.17	_	_	0.17	_	_	_	_	_	_	UI
(peak-to-peak)	Pattern = CJPAT													
Total jitter	Data rate = 3.75 Gbps			0.35		_	0.35	_				_	_	UI
(peak-to-peak)	Pattern = CJPAT			0.00			0.00							01
HiGig Receiver Jit	ter Tolerance <i>(7)</i>	I		I	ı				I	I	I			
Deterministic jitter tolerance	Data rate = 3.75 Gbps		> 0.37			> 0.3	7	_	_	_	_	_	_	UI
(peak-to-peak)	Pattern = CJPAT													
Combined deterministic and random jitter tolerance (peak-to-peak)	Data rate = 3.75 Gbps Pattern = CJPAT		> 0.65			> 0.6	5	_	_	_	_	_	_	UI
	Jitter frequency = 22.1 KHz													
	Data rate = 3.75 Gbps		> 8.5			> 8.5	j	_	_	_	_	_	_	UI
	Pattern = CJPAT													
Sinusoidal jitter	Jitter frequency = 1.875MHz													
tolerance (peak-to-peak)	Data rate = 3.75 Gbps		> 0.1			> 0.1		_		_		_	_	UI
	Pattern = CJPAT													
	Jitter frequency = 20 MHz													
	Data rate = 3.75 Gbps		> 0.1		> 0.1		_	_	_	_	_	_	UI	
	Pattern = CJPAT													

Table 1-40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 5 of 10)

Symbol/	0		13			C4			C5, I	5		C6		
Description	Conditions	Min	Тур	Max	Unit									
SDI Transmitter J	itter Generation <i>(8)</i>													
Alignment jitter	Data rate = 1.485 Gbps (HD) pattern = Color Bar Low- frequency Roll-off = 100 KHz	0.2	_	_	0.2		_	0.2	_	_	0.2		_	UI
(peak-to-peak)	Data rate = 2.97 Gbps (3G) pattern = Color bar Low- frequency Roll-off = 100 KHz	0.3	_	_	0.3		_	0.3	_	_	0.3		_	UI
SDI Receiver Jitter Tolerance (8)											•			
	Jitter frequency = 15 KHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble		> 2			> 2			> 2			> 2		UI
	color bar Jitter frequency = 100 KHz													
Sinusoidal jitter tolerance (peak-to-peak)	Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar		> 0.3			> 0.3			> 0.3			> 0.3		UI
	Jitter frequency = 148.5 MHz													
	Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar		> 0.3			> 0.3			> 0.3			> 0.3		UI

Table 1-40. Tran	nsceiver Block Jitter	Specifications for	Arria II GX Devices	(Note 1)	(Part 10 of 10)
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Symbol/	Conditions		13			C4			C5, IS	5		C6		Unit
Description	Collultions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	UIIIL
	Jitter frequency = 21.8 KHz		> 8.5			> 8.5			> 8.5			> 8.5		UI
Sinusoidal jitter	Pattern = CJPAT													
tolerance at 3072 Mbps	Jitter frequency = 1843.2 KHz to 20 MHz		> 0.1			> 0.1			> 0.1			> 0.1		UI
	Pattern = CJPAT													

Notes to Table 1-40:

- (1) Dedicated refelk pins are used to drive the input reference clocks. The jitter numbers are valid for the stated conditions only.
- (2) The jitter numbers for SONET/SDH are compliant to the GR-253-CORE Issue 3 Specification.
- (3) The jitter numbers for XAUI are compliant to the IEEE802.3ae-2002 Specification.
- (4) The jitter numbers for PCle are compliant to the PCle Base Specification 2.0.
- (5) The jitter numbers for SRIO are compliant to the RapidIO Specification 1.3.
- (6) The jitter numbers for GIGE are compliant to the IEEE802.3-2002 Specification.
- (7) The jitter numbers for HiGig are compliant to the IEEE802.3ae-2002 Specification.
- (8) The HD-SDI and 3G-SDI jitter numbers are compliant to the SMPTE292M and SMPTE424M Specifications.
- (9) Arria II PCIe receivers are compliant to this specification provided the VTX_CM-DC-ACTIVEIDLE-DELTA of the upstream transmitter is less than 50 mV.
- (10) The jitter numbers for Serial Advanced Technology Attachment (SATA) are compliant to the Serial ATA Revision 3.0 Specification.
- (11) The jitter numbers for Common Public Radio Interface (CPRI) are compliant to the CPRI Specification V3.0.
- (12) The jitter numbers for Open Base Station Architecture Initiative (OBSAI) are compliant to the OBSAI RP3 Specification V4.1.

Table 1–41 lists the transceiver jitter specifications for all supported protocols for Arria II GZ devices.

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices (Note 1), (2) (Part 1 of 7)

Symbol/	Oouditions.		-C3 and	–13	-	-C4 and	–14	11
Description	Conditions	Min	Тур	Max	Min	Тур	Max	Unit
SONET/SDH Transmit Jitter Gener	ation <i>(3)</i>							
Peak-to-peak jitter at 622.08 Mbps	Pattern = PRBS15	_	_	0.1	_	_	0.1	UI
RMS jitter at 622.08 Mbps	Pattern = PRBS15	_	_	0.01	_	_	0.01	UI
Peak-to-peak jitter at 2488.32 Mbps	Pattern = PRBS15	_	_	0.1	_	_	0.1	UI
RMS jitter at 2488.32 Mbps	Pattern = PRBS15	_	_	0.01	_	_	0.01	UI
SONET/SDH Receiver Jitter Tolera	ance <i>(3)</i>							
	Jitter frequency = 0.03 KHz		> 15			> 15		UI
	Pattern = PRBS15		/ 10			/ 10		
Jitter tolerance at 622.08 Mbps	Jitter frequency = 25 KHZ		> 1.5			> 1.5		UI
	Pattern = PRBS15							
	Jitter frequency = 250 KHz		> 0.15	•		> 0.15	:	UI
	Pattern = PRBS15		> 0.10	,		> 0.10		01

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices (Note 1), (2) (Part 7 of 7)

Symbol/ Description			-C3 and	–13		-C4 and	–14	
	Conditions	Min	Тур	Max	Min	Тур	Max	- Unit
OBSAI Receiver Jitter Tolerance	(15)			<u>I</u>				
Deterministic jitter tolerance at 768 Mbps, 1536 Mbps, and 3072 Mbps	Pattern = CJPAT		> 0.37	,		> 0.37		UI
Combined deterministic and random jitter tolerance at 768 Mbps, 1536 Mbps, and 3072 Mbps	Pattern = CJPAT		> 0.55	i		> 0.55		UI
Sinusoidal jitter tolerance at 768 Abps	Jitter frequency = 5.4 KHz Pattern = CJPAT		> 8.5			> 8.5		UI
	Jitter frequency = 460 MHz to 20 MHz Pattern = CJPAT		> 0.1			> 0.1		UI
Sinusoidal jitter tolerance at	Jitter frequency = 10.9 KHz Pattern = CJPAT		> 8.5			> 8.5		UI
1536 Mbps	Jitter frequency = 921.6 MHz to 20 MHz Pattern = CJPAT		> 0.1			> 0.1		UI
inusoidal jitter tolerance at 072 Mbps	Jitter frequency = 21.8 KHz Pattern = CJPAT		> 8.5			> 8.5		UI
	Jitter frequency = 1843.2 MHz to 20 MHz Pattern = CJPAT		> 0.1			> 0.1		UI

Notes to Table 1-41:

- (1) Dedicated refclk pins were used to drive the input reference clocks.
- (2) The jitter numbers are valid for the stated conditions only.
- (3) The jitter numbers for SONET/SDH are compliant to the GR-253-CORE Issue 3 Specification.
- (4) The jitter numbers for Fibre Channel are compliant to the FC-PI-4 Specification revision 6.10.
- (5) The Fibre Channel transmitter jitter generation numbers are compliant to the specification at the δ_T inter operability point.
- (6) The Fibre Channel receiver jitter tolerance numbers are compliant to the specification at the δ_R interpretability point.
- $(7) \quad \text{The jitter numbers for XAUI are compliant to the IEEE802.3ae-2002 Specification.}$
- (8) The jitter numbers for PCIe are compliant to the PCIe Base Specification 2.0.
- (9) Arria II GZ PCIe receivers are compliant to this specification provided the $V_{TX-CM-DC-ACTIVEIDLE-DELTA}$ of the upstream transmitter is less than 50 mV.
- (10) The jitter numbers for SRIO are compliant to the RapidIO Specification 1.3.
- (11) The jitter numbers for GIGE are compliant to the IEEE802.3-2002 Specification.
- (12) The HD-SDI and 3G-SDI jitter numbers are compliant to the SMPTE292M and SMPTE424M Specifications.
- (13) The jitter numbers for Serial Attached SCSI (SAS) are compliant to the SAS-2.1 Specification.
- (14) The jitter numbers for CPRI are compliant to the CPRI Specification V3.0.
- (15) The jitter numbers for OBSAI are compliant to the OBSAI RP3 Specification V4.1.

Table 1-53. High-Speed I/O Specifications for Arria II GX Devices (Part 2 of 4)

Cumbal	Conditions	I	3	C	C4 C		,15	C6		Ilmit
Symbol	Conditions	Min	Max	Min	Max	Min	Max	Min	Max	Unit
Transmitter										
	SERDES factor, J = 3 to 10 (using dedicated SERDES)	150	1250 (2)	150	1250 (2)	150	1050 (2)	150	840	Mbps
f _{HSDR_TX} (true LVDS output data rate)	SERDES factor, J = 4 to 10 (using logic elements as SERDES)	(3)	945	(3)	945	(3)	840	(3)	740	Mbps
	SERDES factor, J = 2 (using DDR registers) and J = 1 (using SDR register)	(3)	(3)	(3)	(3)	(3)	(3)	(3)	(3)	Mbps
f _{HSDR_TX_E3R} (emulated LVDS_E_3R output data rate) (7)	SERDES factor, J = 4 to 10	(3)	945	(3)	945	(3)	840	(3)	740	Mbps

Table 1-53.	High-Speed I/O Specifications for Arria II GX Devices	(Part 4 of 4)
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Combal	Conditions	13 C4		34	C5,I5		C6		Ilmit	
Symbol	ol Conditions		Max	Min	Max	Min	Max	Min	Max	Unit
	SERDES factor J = 3 to 10	(3)	945 <i>(7)</i>	(3)	945 <i>(7)</i>	(3)	740 <i>(7)</i>	(3)	640 <i>(7)</i>	Mbps
f _{HSDR} (data rate)	SERDES factor J = 2 (using DDR registers)	(3)	(7)	(3)	(7)	(3)	(7)	(3)	(7)	Mbps
	SERDES factor J = 1 (using SDR registers)	(3)	(7)	(3)	(7)	(3)	(7)	(3)	(7)	Mbps
Soft-CDR PPM tolerance	Soft-CDR mode	_	300	_	300	_	300	_	300	±PPM
DPA run length	DPA mode	_	10,000	_	10,000	_	10,000	_	10,000	UI
Sampling window (SW)	Non-DPA mode (5)	_	300	_	300	_	350	_	400	ps

Notes to Table 1-53:

- (1) $f_{HSCLK_IN} = f_{HSDR} / W$. Use W to determine the supported selection of input reference clock frequencies for the desired data rate.
- (2) Applicable for interfacing with DPA receivers only. For interfacing with non-DPA receivers, you must calculate the leftover timing margin in the receiver by performing link timing closure analysis. For Arria II GX transmitter to Arria II GX non-DPA receiver, the maximum supported data rate is 945 Mbps. For data rates above 840 Mbps, perform PCB trace compensation by adjusting the PCB trace length for LVDS channels to improve channel-to-channel skews.
- (3) The minimum and maximum specification depends on the clock source (for example, PLL and clock pin) and the clock routing resource you use (global, regional, or local). The I/O differential buffer and input register do not have a minimum toggle rate.
- (4) The specification is only applicable under the influence of core noise.
- (5) Applicable for true LVDS using dedicated SERDES only.
- (6) Dedicated SERDES and DPA features are only available on the right banks.
- (7) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and the receiver sampling margin to determine the leftover timing margin.

Table 1–54 lists the high-speed I/O timing for Arria II GZ devices.

Table 1-54. High-Speed I/O Specifications for Arria II GZ Devices (Note 1), (2), (10) (Part 1 of 3)

Cumbal	Conditions	C3, I3			C4, I4			II.u.!4
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Unit
Clock	Clock							
f _{HSCLK_in} (input clock frequency) true differential I/O standards	Clock boost factor W = 1 to 40 (3)	5	_	717	5	_	717	MHz
f _{HSCLK_in} (input clock frequency) single ended I/O standards (9)	Clock boost factor W = 1 to 40 (3)	5	_	717	5	_	717	MHz
f _{HSCLK_in} (input clock frequency) single ended I/O standards (10)	Clock boost factor W = 1 to 40 (3)	5	_	420	5	_	420	MHz

Table 1-54. High-Speed I/O Specifications for Arria II GZ Devices (Note 1), (2), (10) (Part 2 of 3)

O	O and Hillians	C3, I3						
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Unit
f _{HSCLK_OUT} (output clock frequency)	_	5	_	717 (7)	5		717 (7)	MHz
Transmitter								
(SERDES factor, $J = 3$ to 10 (using dedicated SERDES) (8)	(4)	_	1250	(4)	_	1250	Mbps
f _{HSDR} (true LVDS output data rate)	SERDES factor J = 2, (using DDR registers)	(4)	_	(5)	(4)	_	(5)	Mbps
	SERDES factor J = 1, (uses an SDR register)	(4)	_	(5)	(4)	_	(5)	Mbps
f _{HSDR} (emulated LVDS_E_3R output data rate) (5)	SERDES factor J = 4	(4)	_	1152	(4)	_	800	Mbps
f _{HSDR} (emulated LVDS_E_1R output data rate)	to 10	(4)	_	200	(4)	_	200	Mbps
t _{x Jitter}	Total jitter for data rate, 600 Mbps to 1.6 Gbps	_	_	160	_	_	160	ps
	Total jitter for data rate, < 600 Mbps	_	_	0.1	_	_	0.1	UI
t _{x Jitter} - emulated differential I/O standards with three	Total jitter for data rate, 600 Mbps to 1.25 Gbps	_	_	300	_	_	325	ps
external output resistor network	Total jitter for data rate < 600 Mbps	_	_	0.2	_	_	0.25	UI
t _{x Jitter} - emulated differential I/O standards with one external output resistor network	_	_	_	0.15	_	_	0.15	UI
t _{DUTY}	TX output clock duty cycle for both True and emulated differential I/O standards	45	50	55	45	50	55	%

Table 1–57. External Memory Interface Specifications for Arria II GX Devices (Part 2 of 2)

Frequency Range (MHz)		Resolution	DQS Delay	Number of		
Mode	C4	13, C5, 15	C6	(°)	Buffer Mode (1)	Delay Chains
5	270-410	270-380	270-320	36	High	10
6	320-450	320-410	320-370	45	High	8

Note to Table 1-57:

(1) Low indicates a 6-bit DQS delay setting; high indicates a 5-bit DQS delay setting.

Table 1–58 lists the DLL frequency range specifications for Arria II GZ devices.

Table 1–58. DLL Frequency Range Specifications for Arria II GZ Devices

Funnament Made	Frequency F	Range (MHz)	Ausilahla Dhaaa Chiff	DQS Delay	Number of
Frequency Mode	-3	-4	Available Phase Shift	Buffer Mode (1)	Delay Chains
0	90-130	90-120	22.5°, 45°, 67.5°, 90°	Low	16
1	120-170	120-160	30°, 60°, 90°, 120°	Low	12
2	150-210	150-200	36°, 72°, 108°, 144°	Low	10
3	180-260	180-240	45°, 90°,135°, 180°	Low	8
4	240-320	240-290	30°, 60°, 90°, 120°	High	12
5	290-380	290-360	36°, 72°, 108°, 144°	High	10
6	360-450	360-450	45°, 90°, 135°, 180°	High	8
7	470-630	470-590	60°, 120°, 180°, 240°	High	6

Note to Table 1-58:

(1) Low indicates a 6-bit DQS delay setting; high indicates a 5-bit DQS delay setting.

Table 1–59 lists the DQS phase offset delay per stage for Arria II GX devices.

Table 1-59. DQS Phase Offset Delay Per Setting for Arria II GX Devices (Note 1), (2), (3)

Speed Grade	Min	Max	Unit
C4	7.0	13.0	ps
I3, C5, I5	7.0	15.0	ps
C6	8.5	18.0	ps

Notes to Table 1-59:

- (1) The valid settings for phase offset are -64 to +63 for frequency modes 0 to 3 and -32 to +31 for frequency modes 4 to 5.
- (2) The typical value equals the average of the minimum and maximum values.
- (3) The delay settings are linear.

Table 1-68. Glossary (Part 3 of 4)

Letter	Subject	Definitions				
S	Sw (sampling window) Single-ended Voltage Referenced I/O Standard	The period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window: Timing Diagram Bit Time				
	t _C	High-speed receiver and transmitter input and output clock period.				
	TCCS (channel-to- channel- skew)	The timing difference between the fastest and slowest output edges, including t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the <i>Timing Diagram</i> figure under S in this table).				
		High-speed I/O block: Duty cycle on the high-speed transmitter output clock.				
T	t _{DUTY}	Timing Unit Interval (TUI) The timing budget allowed for skew, propagation delays, and data sampling window. (TUI = $1/(\text{Receiver Input Clock Frequency Multiplication Factor}) = t_{\text{C}}/w)$				
	t _{FALL}	Signal high-to-low transition time (80-20%)				
	t _{INCCJ}	Cycle-to-cycle jitter tolerance on the PLL clock input.				
	t _{OUTPJ_IO}	Period jitter on the general purpose I/O driven by a PLL.				
		Period jitter on the dedicated clock output driven by a PLL.				
	t _{OUTPJ_DC}	Torrod fitter on the dedicated crook output arriver by a T EE.				